

Abstract

Electronic component with a housing package

The invention relates to an electronic component with a housing package (2) comprising a number of layers of plastic (3) with at least one buried interconnect layer (4) and with at least one semiconductor chip (5), which has pointed-conical external contacts (7) distributed on an outer side (6). The pointed-conical external contacts (7) penetrate through one of the layers of plastic (3) and form contact vias with respect to the buried interconnect layer (4). Furthermore, the invention relates to a method for producing such an electronic component (1).

[Figure 1]